

MVGSF1N03LT1G-VB Datasheet N-Channel 20 V (D-S) MOSFET

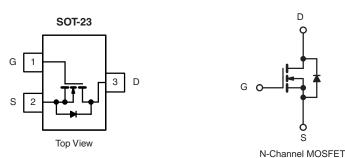
PRODUCT SUMMARY							
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^e	Q _g (Typ.)				
	0.022 at V _{GS} = 4.5 V	6 ^a					
20	0.028 at V _{GS} = 2.5 V	6 ^a	8.8 nC				
	0.039 at V _{GS} = 1.8 V	5.6					

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- DC/DC Converters
- Load Switch for Portable Applications



Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 12	V	
	T _C = 25 °C		6 ^a		
Continuous Drain Current (T 150 °C)	T _C = 70 °C		5.1		
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	T _A = 25 °C		5 ^{b, c}		
	T _A = 70 °C		4 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	20		
Continuous Course Drain Diado Current	T _C = 25 °C		1.75		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.04 ^{b, c}		
	T _C = 25 °C		2.1		
Movimum Dower Discinction	T _C = 70 °C		1.3	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.25 ^{b, c}	vv	
	T _A = 70 °C		0.8 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Tempera		260			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	80	100	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	60	0/11	

Notes:

a. Package limited

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under steady state conditions is 125 °C/W.

e. Based on T_C = 25 °C.



FREE

Parameter Static

SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted

Symbol

			B	® VBse	
			www.v	/Bsemi.co	
ed					
Test Conditions	Min.	Тур.	Max.	Unit	
		•	•		
_{GS} = 0 V, I _D = 250 µA	20			V	
I _D = 250 μA		25		····)//00	
I _D = 250 μA		- 2.6		mV/°C	
_{DS} = V _{GS} , I _D = 250 μA	0.45		1.0	V	
_{DS} = 0 V, V _{GS} = ± 8 V			± 100	nA	
_{DS} = 20 V, V _{GS} = 0 V			1		
	-			μA	

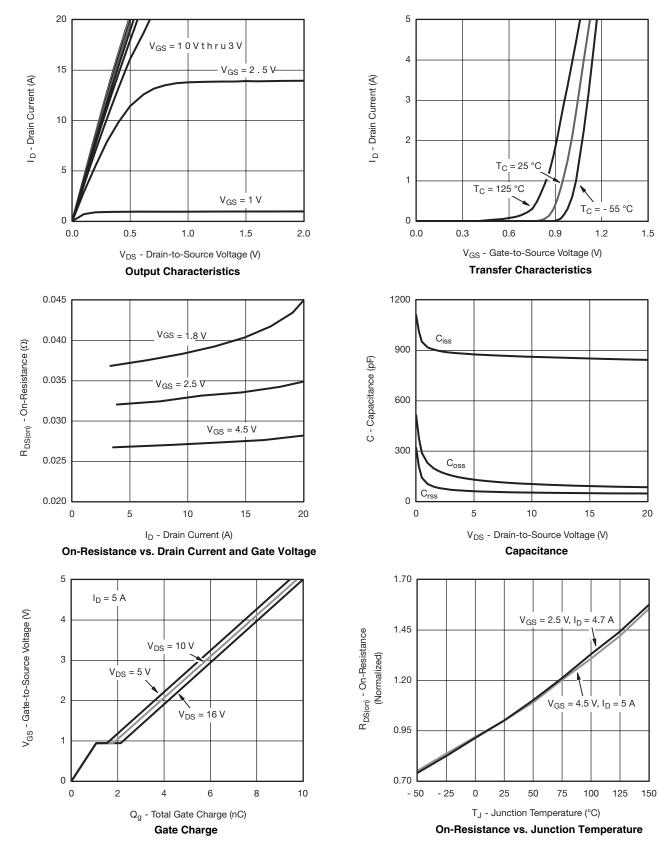
otatio						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		25		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}\!/T_J$	J		- 2.6		1110/ 0
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	0.45		1.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 8 V$			± 100	nA
	I _{DSS}	$V_{DS} = 20 V, V_{GS} = 0 V$			1	μA
Zero Gate Voltage Drain Current	USS	V_{DS} = 20 V, V_{GS} = 0 V, T_{J} = 70 °C			10	μΛ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \leq 5$ V, V_{GS} = 4.5 V	20			А
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$		0.022		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 4.7 \text{ A}$		0.028		Ω
		$V_{GS} = 1.8 \text{ V}, \text{ I}_{D} = 4.3 \text{ A}$		0.039		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$		24		S
Dynamic ^b						
Input Capacitance	C _{iss}			865		
Output Capacitance	C _{oss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz		105		pF
Reverse Transfer Capacitance	C _{rss}			55		
Total Cata Charge	0	V_{DS} = 10 V, V_{GS} = 5 V, I_{D} = 5.0 A		12	18	nC
Total Gate Charge	Qg			8.8	14	
Gate-Source Charge	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 5.0 A		1.1		
Gate-Drain Charge	Q _{gd}			0.7		
Gate Resistance	Rg	f = 1 MHz	0.5	2.4	4.8	Ω
Turn-On Delay Time	t _{d(on)}			8	16	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		17	26	ns
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 4$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		31	47	
Fall Time	t _f			8	16	
Turn-On Delay Time	t _{d(on)}			5	10	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		13	20	-
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong \text{4}$ A, V_GEN = 5 V, R_g = 1 Ω		21	32	
Fall Time	t _f			6	12	
Drain-Source Body Diode Characteristic	s		•	•	•	
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			1.75	А
Pulse Diode Forward Current	I _{SM}				20	~
Body Diode Voltage	V _{SD}	$I_{S} = 4 \text{ A}, V_{GS} = 0 \text{ V}$		0.75	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			12	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 4 A, dl/dt = 100 A/μs, T _J = 25 °C		5	10	nC
Reverse Recovery Fall Time	t _a	$r_{\rm F} = 4$ A, $u/u_{\rm I} = 100$ A/µs, $r_{\rm J} = 25$ °C		7		200
Reverse Recovery Rise Time	t _b			5	1	ns

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.







 $I_D = 5 A$

T_J = 125 °C

 $T_J = 25 \ ^{\circ}C$

6

10

100

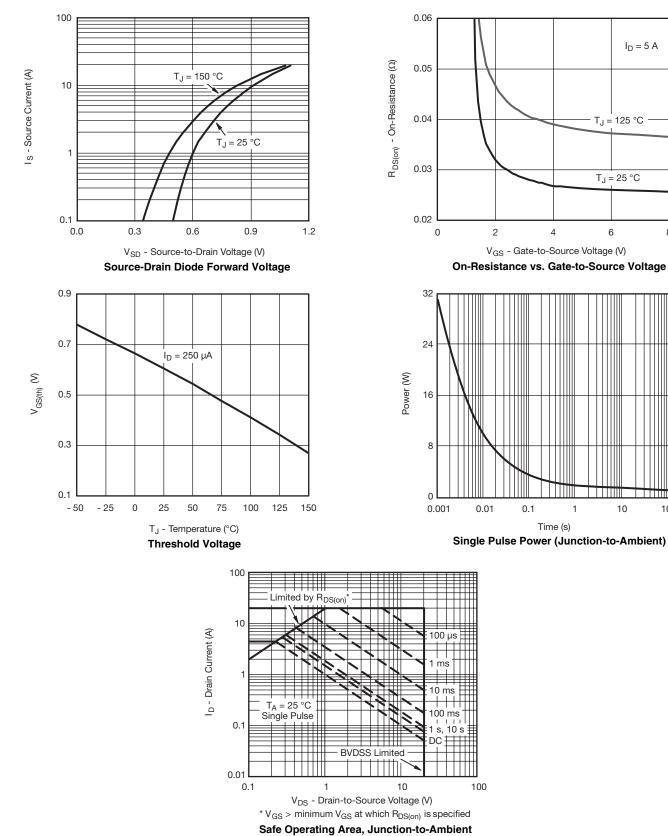
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Time (s)

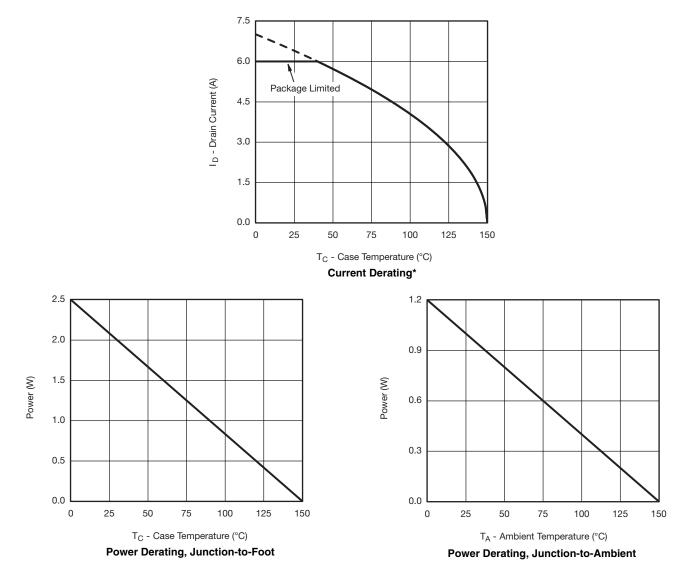
8

4

0.1

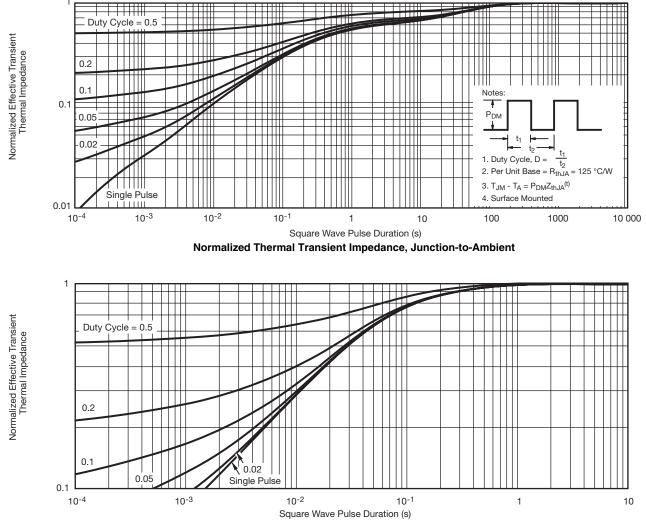






* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

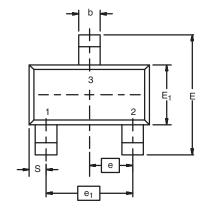


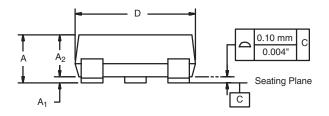


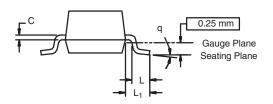
Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95	5 BSC	0.0374 Ref		
e ₁	1.90) BSC	0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3 °	8°	3°	8 °	
ECN: S-03946-Rev. K, 09- DWG: 5479	Jul-01				

MVGSF1N03LT1G-VB



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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